

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S1 | 168 | wafer with sensor\$4 with top with bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/01 13:21 |
| S3 | 26 | silicon with wafer with sensor\$4 with top with bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/01 13:21 |
| S5 | 15 | wafer with sensor\$4 with (build\$4 or fabricat\$4) with top with bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/01 13:33 |
| S18 | 17 | silicon with sensor\$4 with (build\$4 or fabricat\$4) with top with bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/01 13:47 |